DIAMOND SCRUB PAD

NEW GENERATION

Product description

DSP pads are a new generation of scrubbing tools, developed for Preventive Maintenance Cleanings of Semiconductor equipment. Pure diamonds are coated on a polyamide film (Mylar). They are available in various diamond sizes and pad shapes.

Designed for higher productivity

Faster	cleaning
Less	generation of particles and contaminations
Shorter	tool requalification time
Shorter	total Preventive Maintenance time
Longer	Maintenance interval
Longer	tool Production availability
Suitable for preventing damage	on critical surfaces such as anodized aluminum, ceramics, etc.

Application chart

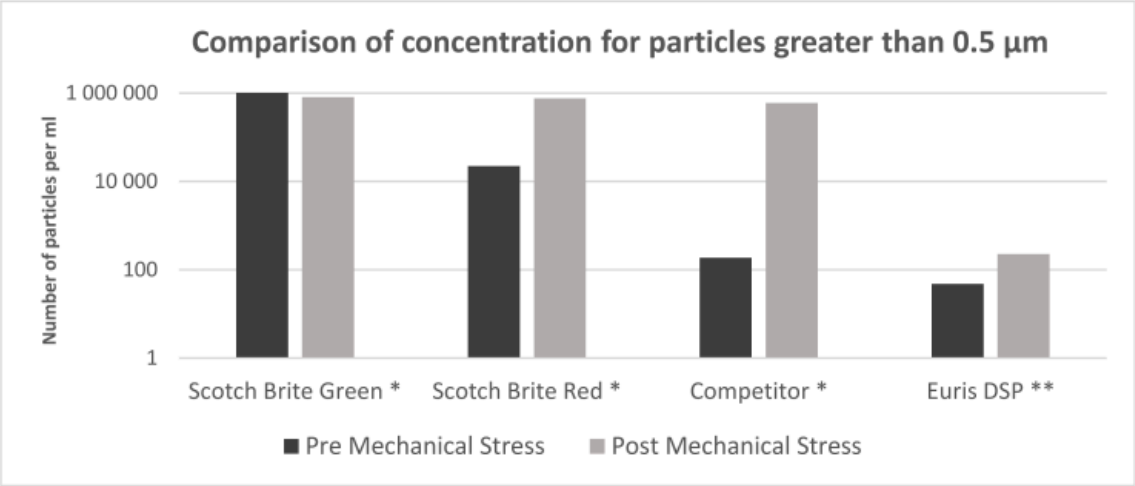
DSP part #		ALD CVD Etch	Implant	CMP
250-F-1 	250-L-1 	**Heavy duty for hard process residue** Alcatel AMAT Genus ALD Novellus Oxford Picosun Plasmatherm Roth & Rau	**Source, Chamber, Residue** AMAT Axcelis Eaton Varian	
600-F-1	600-L-1	**Heavy duty for hard process residue** Alcatel AMAT Axcelis Novellus Hitachi LAM Novellus Oxford Picosun Plasmatherm Roth & Rau TEL		
1600-F-1	1600-L-1	**Heavy duty for hard process residue** Alcatel AMAT Axcelis Novellus Hitachi LAM Novellus Oxford Picosun Plasmatherm Roth & Rau TEL		**Dried slurry** AMAT Ebara G&P IPEC Strasbaugh Westec Wolters
3000-F-1	3000-L-1	**Heavy duty for hard process residue** Alcatel AMAT Axcelis Novellus Hitachi LAM Novellus Oxford Picosun Plasmatherm Roth & Rau TEL	**Polish source chamber, liner and source bushing** AMAT Axcelis Eaton Varian	**Dried slurry residue** AMAT Ebara G&P IPEC Strasbaugh Westec Wolters

General specification

Composition:	Diamond abrasive aggregate free	**Diamond Sizes:**	6µm, 12µm, 35µm, 80µm...
Substrate:	Low particle emission PET film - Mylar	**Bonding:**	Acrylate type structured by PET
Pad Shape:	60X90mm or ø 90mm	**Back side:**	Loop or PE hydrophobic foam

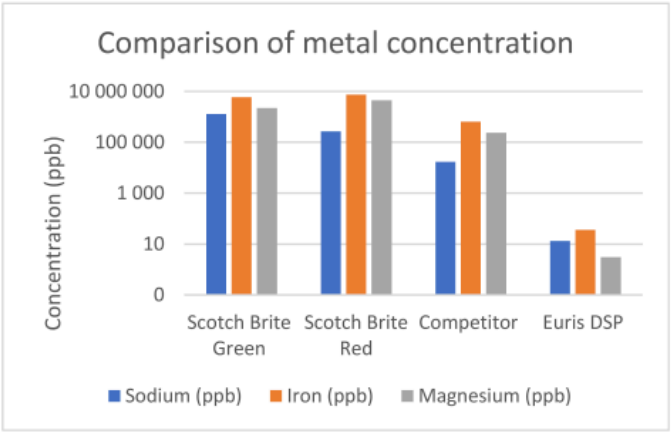
Analytical analysis

Particles - LPC (Liquid Particle Count)



	Number of particles per millilitre			
Particles size > 0.5 µm	**Scotch Brite Green ***	**Scotch Brite Red ***	**Competitor ***	**Euris DSP ****
Pre Mechanical Stress	2.430.000	22.356	186	48
Post Mechanical Stress	810.000	756.000	594.000	226

IONS - ICP-MS (Inductively Coupled Plasma Mass Spectrometry)



Extracted Ions	Scotch Brite Green ***	Scotch Brite Red ***	Competitor ***	Euris DSP ****
Sodium (ppb)	1.300.000	270.000	17.000	13
Iron (ppb)	5.950.000	7.400.000	641.000	36
Magnesium (ppb)	2.200.000	4.400.000	233.000	3

*	Based on Competitor Website Data
**	Based on ECP Analysis CERT 210632 Data
***	Data from Competitor Website
****	ECP Analysis CERT 210656 Data

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